

Honeywell's Docket No. JM36978 CIP2 (4962)  
Practitioner's Docket No. 52-015-004

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Box Non-Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231**

**POWER OF ATTORNEY BY ASSIGNEE OF ENTIRE INTEREST  
(REVOCATION OF PRIOR POWERS)**

As assignee of record of the entire interest of the above identified application,

**REVOCATION OF PRIOR POWERS OF ATTORNEY**

all powers of attorney previously given are hereby revoked and

**NEW POWER OF ATTORNEY**

the following practitioner is hereby appointed to prosecute and transact all business in the Patent and Trademark Office connected therewith.

Sandra P. Thompson, Registration No. 46264  
Roger H. Criss, Registration No. 25570  
Melanie Brown, Registration No. 31592  
Curtis Brueske, Registration No. 33839  
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Application No.	Filing Date	Title	Reel/Frame No.	Status
09/543628	04/05/00	Novel/Polymer Substrate and Polymer/Polymer Interfaces	Assignment Filed 04/18/00, Reel/Frame No. Not Yet Assigned	Pending
10/113461	03/28/02	Novel/Polymer Substrate and Polymer/Polymer Interfaces	Not Yet Assigned	Pending
07/804116	12/06/91	Rapid-Curing Adhesive Formulation for Semiconductor Devices	6012/0910	Issued
09/398988	09/17/99	Compliant and Crosslinkable Thermal Interface Materials	9824/0333	Issued
09/774466	01/30/01	Compliant and Crosslinkable Thermal Interface Materials	9824/0333	Allowed
09/439249	11/12/99	Via Fill Formulations Which Are Electrically and/or Thermally Conductive, or Non-Conductive	010394/0130	Issued
08/272354	07/08/94	Metal-Ceramic Composite Lid	7201/0955	Issued
08/089370	07/09/93	Sealing Glass Compositions	6628/0018	Issued
10/300493	11/18/02	Moisture Resistant, Flexible Epoxy/Cyanate Ester Formulations	Not Yet Filed	Pending
09/265292	03/09/99	Compliant and Crosslinkable Thermal Interface Materials	9824/0333	Issued
09/416706	10/12/99	Method of Applying a Die Attach Adhesive	9391/0237	Issued
09/452483	12/01/99	Thermal Interface Materials	010432/0436	Issued
10/047617	01/14/02	Thermal Interface Materials	012730/0809	Pending

10/242139	09/09/02	Thermal Interface Materials	Assignment Filed 11/18/02, but Reel/Frame No. Not Yet Assigned	Pending
09/851103	05/07/01	Polymer Solder	Assignment Filed 05/07/01, but Reel/Frame No. Not Yet Assigned	Pending
09/726066	11/29/00	Models and Methods of Integrating Simulation Techniques for Advanced Material Predictive Analysis	Assignment Filed 01/10/01, but Reel/Frame No. Not Yet Assigned	Pending
10/326233	12/19/02	Models and Methods of Integrating Simulation Techniques for Advanced Material Predictive Analysis	Not Yet Filed	Pending
09/818324	03/26/01	Compliant Pre-Form Interconnect	011647/0318	Allowed

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Date

4/14/03



Shannon Votava

Title: Assistant Secretary  
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